

# ISMP 2021

## The 19<sup>th</sup> International Symposium on Microelectronics and Packaging

Special Symposium to Honor Retirement of Professor Kyung W. Paik

**November 3(Wed.)~5(Fri.), 2021, Busan, Korea**

Hybrid (both onsite face-to-face and online sessions) Symposium

### INVITATION

It is our great pleasure to announce that the 19<sup>th</sup> International Symposium on Microelectronics and Packaging (ISMP cor2021) will be held as hybrid meeting (both onsite face-to-face and online sessions) at Busan, Korea, on November 3(Wed.)~5(Fri.), 2021. The ISMP 2021, organized by KMEPS (the Korean Microelectronics and Packaging Society), presents a valuable chance to share the latest electronic packaging technologies with other professionals as well as to boost communication and collaboration with colleagues around the world. The ISMP 2021 organizing committee promises to provide an outstanding and fruitful program, which will be a great opportunity that you do not miss. Also, ISMP 2021 inaugurates special symposium in memory and in recognition of the scientific contributions of Professor Kyung W. Paik. We cordially invites you to submit abstracts for oral and poster presentation. We look forward to meeting you at ISMP 2021 in November.

### SYMPOSIUM TOPICS

ISMP 2021 will include all basic/applied sciences and technologies in the fields of electronic materials, devices, and packaging. Topics may include, but are not limited to, the following areas:

1. Novel Packaging Technologies for AI, IoT, and Big data
2. Packaging Solutions for 5G/6G Applications
3. System Integration with Advanced Packaging Technologies
4. Electronic Materials for Interconnects and Packaging
5. Emerging Process for Interconnects and Packaging
6. PCB, Solder, and Assembly Process
7. Automotive & Power Electronic Packaging
8. Sensors, LED, and Emerging Packaging Technology
9. Flexible, Wearable, and Printed Electronics
10. MEMS/NEMS Packaging and Applications
11. Reliability of Electronic Devices and Systems
12. Design Tools and Modeling

### IMPORTANT DATES

Submission of Abstract	<b>July 30, 2021</b>
Notification of Acceptance	<b>August 31, 2021</b>
Pre-registration	<b>October 25, 2021</b>
Symposium	<b>November 3-5, 2021</b>
Submission of Final Manuscript	<b>December 31, 2021</b>

### CONFERENCE LANGUAGE

The official language of the symposium is English.

### SYMPOSIUM SECRETARIAT (CONTACT)

Ms. Minjin Kim (KMEPS)  
Tel: +82-2-538-0962, Fax: +82-2-538-0963  
E-mail: [kmeps@ismp2021.org](mailto:kmeps@ismp2021.org)

Visit the ISMP 2021 website (<http://ismp2021.org/>) for additional symposium information.  
Organized by The Korean Microelectronics and Packaging Society (KMEPS)